



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C64M32MD2A-25BIN							
Part Weight(g):		0.189791							
NO.	Material	Supplier	Type	Substances	Purpose	CAS No.	Weight (mg)	wt % of Total unit wt	PPM
1	Molding Compound	Sumitomo	G760LB				103.474	54.52%	545,200
				2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diyl)-bis(oxymethylene))-bis-oxirane	Resin	Trade Secret	8.278	8.00%	43,616
				Phenol Resin A	Resin	Trade Secret	3.104	3.00%	16,356
				Phenol Resin B	Resin	Trade Secret	3.104	3.00%	16,356
				Silica(Amorphous) A	Base material	60676-86-0	72.432	70.00%	381,640
				Silica(Amorphous) B	Base material	7631-86-9	7.761	7.50%	40,890
				Metal Hydroxide	Base material	Trade Secret	8.278	8.00%	43,616
				Carbon Black	Additive	1333-86-4	0.517	0.50%	2,726
2	Substrate	Ryowa	BT				51.775	27.28%	272,800
3	DAF	Nitto	EM760				1.310	0.69%	6,900
				Acrylic resin	Base material	Trade Secret	0.655	50.00%	3,450
				Silica, amorphous	Base material	7631-86-9	0.589	45.00%	3,105
				Phenol resin	Base material	Trade Secret	0.065	5.00%	345
4	Wire	MKE	Au 0.8mil				1.348	0.71%	7,100
				GOLD	Base material	7440-57-5	1.3474	99.99%	7,099
				The others	Base material	Trade Secret	0.0001	0.01%	0.7100
5	Solder Ball	Senju	M705				14.026	7.39%	73,900
				Tin (Sn)	Plating material	7440-31-5	13.535	96.50%	71,314
				Ag	Plating material	7440-22-4	0.421	3.00%	2,217
				Cu	Plating material	7440-50-8	0.070	0.50%	370
6	Die	-		Si	Chip	7440-21-3	17.859	9.41%	94,100
							189.791	100%	1,000,000